TITLE OF THE INVENTION

Process for mechanical chemical polishing of a layer of aluminium or aluminium alloy conducting material.

TEXT OF THE ABSTRACT

Process for mechanical chemical polishing of a layer of an aluminium or aluminium alloy conducting material used in the microelectronics semi-conductors industry in which said aluminium or aluminium alloy layer is abraded using an abrasive composition which comprises an alkaline aqueous suspension of individualized colloidal silica particles not linked to each other by siloxane bonds, a tetraalkylammonium hydroxide and an oxidizing agent.